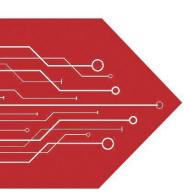
# MSKSEMI















**ESD** 

**TVS** 

**TSS** 

MOV

**GDT** 

**PLED** 

Broduct data speet



#### **Feature**

Ultra Small mold type. SOD-923

Low I<sub>R</sub>

High reliability.

#### **Applications**

Low current rectification

#### **Mechanical Characteristics**

Lead finish:100% matte Sn(Tin)

Mounting position: Any

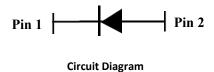
Device meets MSL 1 requirements

Pure tin plating: 7 ~ 17 um

Pin flatness:≤3mil



SOD-923



## Electrical characteristics per line@25℃

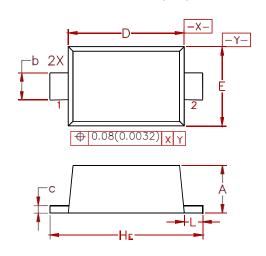
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	V <sub>F</sub>	-	0.27	0.31	V	I <sub>F</sub> =1mA
Forward voltage	V <sub>F</sub>	-	0.30	0.35	V	I <sub>F</sub> =10mA
Forward voltage	V <sub>F</sub>		0.36	0.40	V	I <sub>F</sub> =20mA
Forward voltage	V <sub>F</sub>	-	0.48	0.55	V	I <sub>F</sub> =100mA
Reverse current	I <sub>R</sub>	-	-	1.5	μА	V <sub>R</sub> =10V

## Absolute maximumrating@25℃

Parameter	Symbol	limits	Unit
Reverse voltage (DC)	$V_{RM}$	30	٧
Average rectified forward current	lo	100	mA
Forward current surge peak (60Hz 1cyc)	I <sub>FSM</sub>	500	mA
Operating Junction temperature Range	Tj	-55 to 125	°C
Storage temperature	$T_{stg}$	-40 to +125	°C

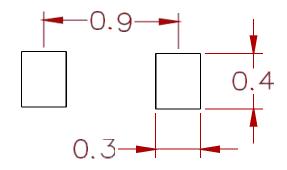


## **PACKAGE MECHANICAL DATA**



	Millimeters			Inches		
Dim	Min	Nom	Max	Min	Nom	Max
Α	0.36	0.40	0.43	0.014	0.016	0.017
b	0.15	0.20	0.25	0.006	0.008	0.010
С	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
E	0.55	0.60	0.65	0.022	0.024	0.026
HE	0.95	1.00	1.05	0.037	0.039	0.041
L	0.05	0.10	0.15	0.002	0.004	0.006

## **Suggested Pad Layout**



**Dimensions: Millimeters** 

## **REEL SPECIFICATION**

P/N	PKG	QTY
RB521CS-30-MS	SOD-923	8000





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